



Material Content Data Sheet



Sales Product Name	SAK-XC2331D-20F66L AA			Issued		29. August 2013		
MA#	MA001053280							
Package	PG-LQFP-64-22			Weight*		369.75 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	17.352	4.69	4.69	46929	46929
leadframe	inorganic material	phosphorus	7723-14-0	0.032	0.01		88	
	non noble metal	zinc	7440-66-6	0.130	0.04		352	
	non noble metal	iron	7439-89-6	2.600	0.70		7031	
	non noble metal	copper	7440-50-8	105.558	28.55	29.30	285487	292958
wire	noble metal	gold	7440-57-5	1.683	0.46	0.46	4551	4551
encapsulation	organic material	carbon black	1333-86-4	1.150	0.31		3111	
	plastics	epoxy resin	-	31.057	8.40		83996	
	inorganic material	silicondioxide	60676-86-0	197.846	53.50	62.21	535084	622191
leadfinish	non noble metal	tin	7440-31-5	4.066	1.10	1.10	10996	10996
plating	noble metal	silver	7440-22-4	1.611	0.44	0.44	4356	4356
glue	plastics	epoxy resin	-	1.666	0.45		4505	
	noble metal	silver	7440-22-4	4.997	1.35	1.80	13514	18019
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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